

N-channel Enhancement Mode Power MOSFET

Features

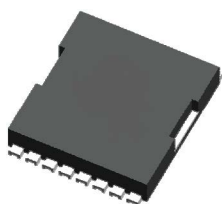
- Very Low On-resistance $R_{DS(ON)}$
- Low C_{rss}
- 100% avalanche tested
- Improved dv/dt capability

Product Summary

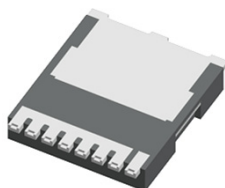
Parameters	Value	Unit
V_{DSS}	60	V
$V_{GS(th_Typ)}$	1.5	V
$I_D(@V_{GS}=10V)$	300	A
$R_{DS(ON_Typ)}(@V_{GS}=10V)$	0.67	$m\Omega$
$R_{DS(ON_Typ)}(@V_{GS}=4.5V)$	1.10	$m\Omega$

Applications

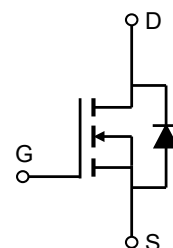
- PWM Application
- Motor drivers
- DC/DC Converter



TOLL-8L Top View



TOLL-8L Bottom View



Schematic Diagram

Device	Marking	Package	Packing	Reel Size	Tape Width	Reel (pcs)
ZK30N100T	30N100	TO-252	Reel	N/A	N/A	2500

MAXIMUM RATINGS ($T_a=25^{\circ}C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^{\circ}C$	I_D	300	A
	$T_C = 100^{\circ}C$		156	
Pulsed Drain Current		I_{DM}	1200	A
Single Pulsed Avalanche Energy		E_{AS}	100	mJ
Power Dissipation		P_D	375	W
Thermal Resistance from Junction to Ambient		$R_{\theta JA}$	60	$^{\circ}C/W$
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 175	$^{\circ}C$

MOSFET ELECTRICAL CHARACTERISTICS

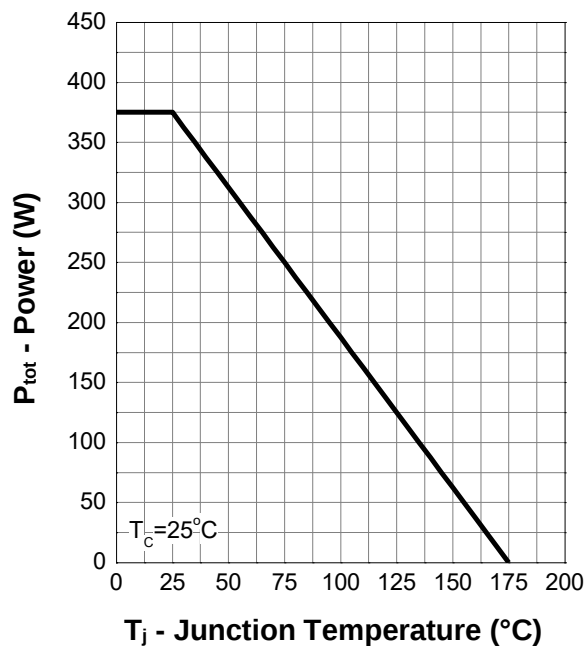
$T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Off characteristics						
Drain-source breakdown voltage	V _{(BR) DSS}	V _{GS} = 0V, I _D = 250 μA	60			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 48V, V _{GS} =0V			1.0	μA
Gate-body leakage current	I _{GSS}	V _{DS} = 0V, V _{GS} =±20V			±100	nA
On characteristics ④						
Gate-threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.0	1.5	2.5	V
Static drain-source on-sate resistance	R _{DS(on)}	V _{GS} =10V, I _D =30A		0.67	0.75	mΩ
		V _{GS} =4.5V, I _D =20A		1.10	1.25	mΩ
Dynamic characteristics ④ ⑤						
Input capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V f =1MHz		7204		pF
Output capacitance	C _{oss}			2154		
Reverse transfer capacitance	C _{rss}			249		
Switching characteristics ④ ⑤						
Total gate charge	Q _g	V _{GS} =0 to 10V V _{DS} =30V, I _D =30A		155		nC
Gate-source charge	Q _{gs}			25		
Gate-drain charge	Q _{gd}			35		
Turn-on delay time	t _{d(on)}	V _{DS} =30V, I _D =30A V _{GS} =10V, R _{GEN} =3.9Ω		16		ns
Turn-on rise time	t _r			56		
Turn-off delay time	t _{d(off)}			149		
Turn-off fall time	t _f			96		
Drain-Source Diode Characteristics						
Drain-source diode forward voltage	V _{SD} ④	V _{GS} =0V, I _{SD} =30A			1.3	V
Continuous drain-source diode forward current	I _S ①	T _C =25℃			140	A
Reverse recovery time	t _{rr}	di/dt = 100A/μs, I _F = 30A		85		ns
Reverse recovery charge	Q _{rr}			120		nC

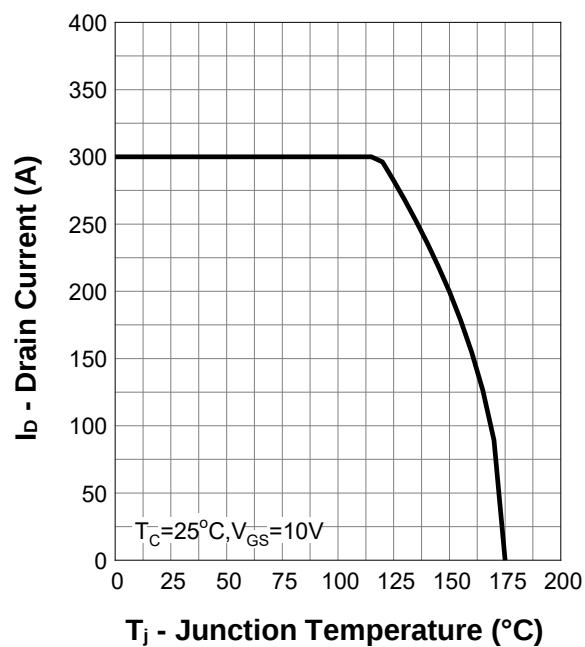
Notes:

1. Guaranteed by design, not subject to production testing
2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycles $\leq 2\%$

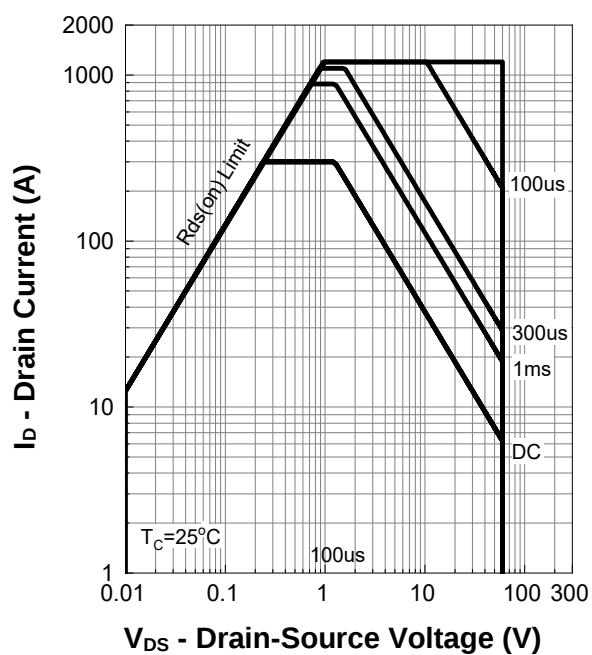
Power Capability



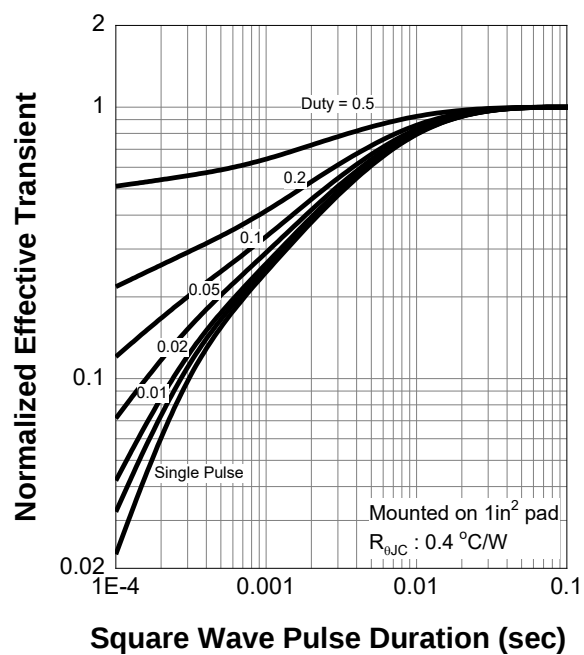
Current Capability

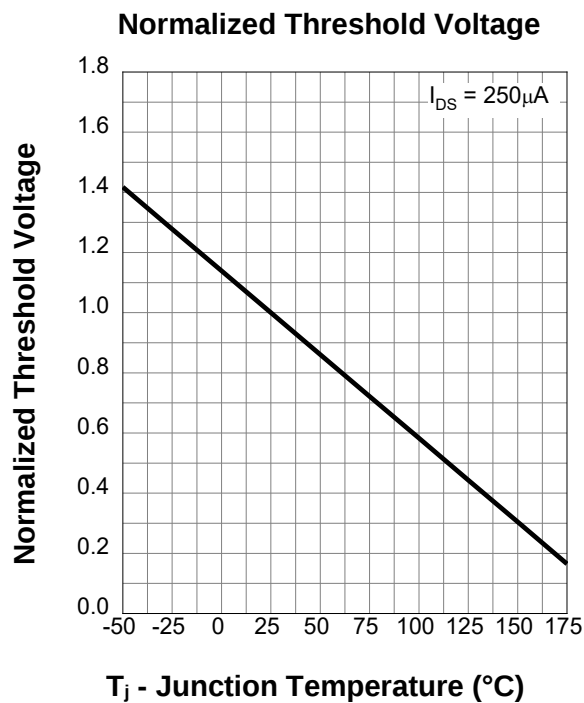
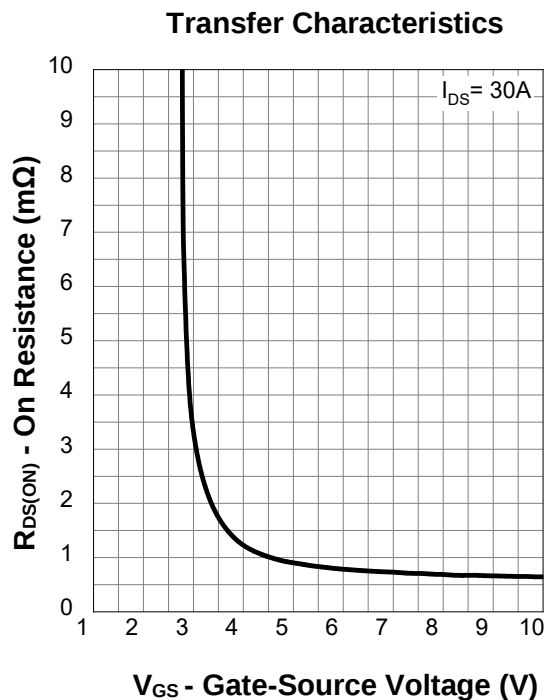
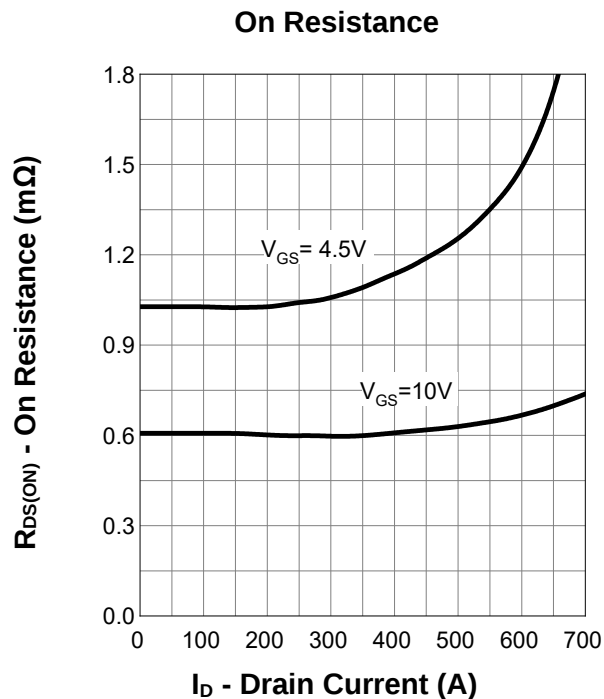
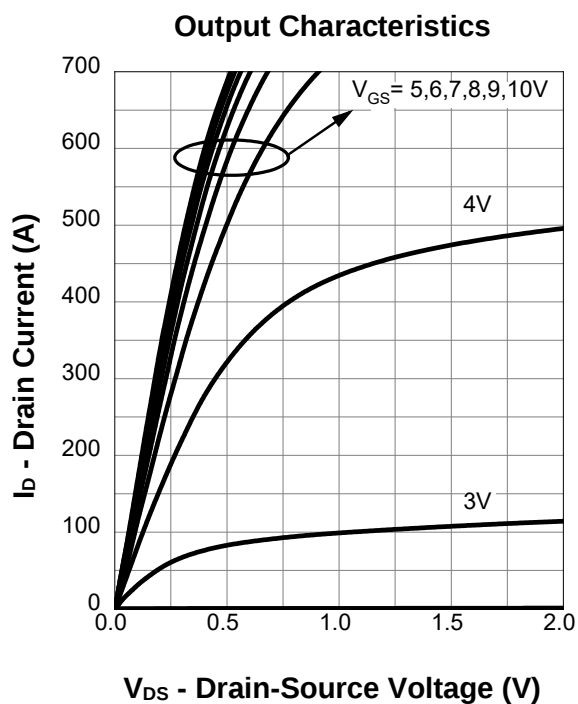


Safe Operation Area

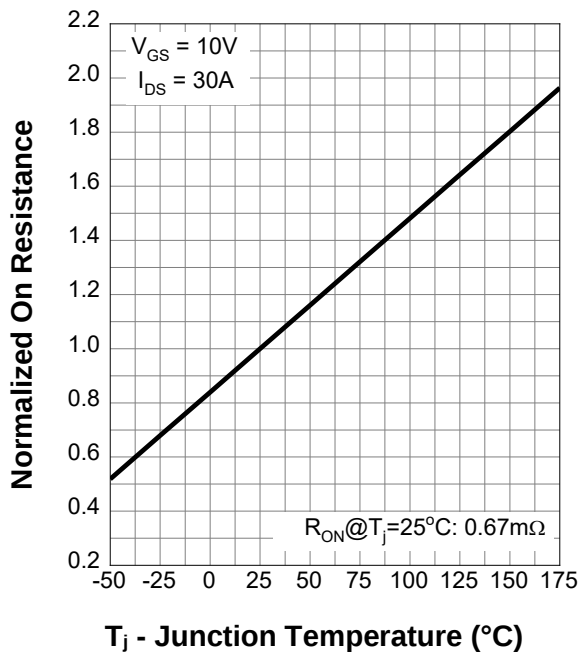


Transient Thermal Impedance

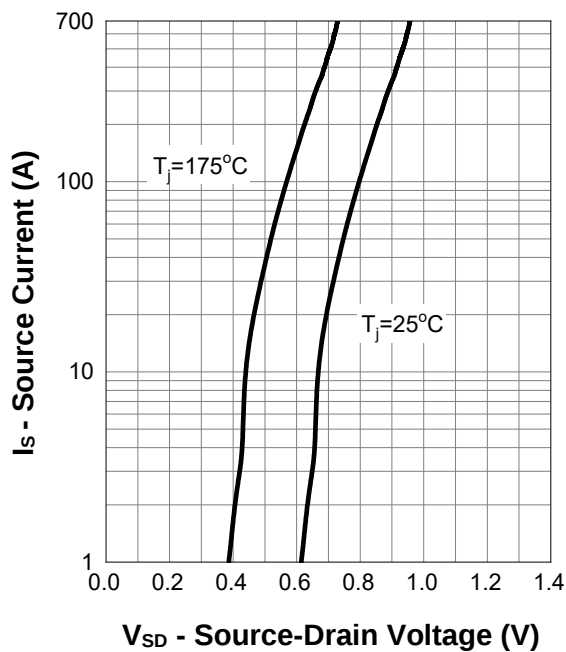




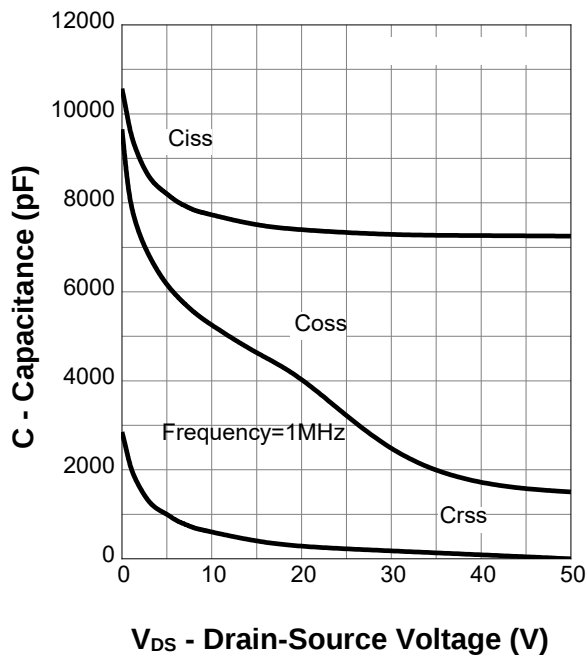
Normalized On Resistance



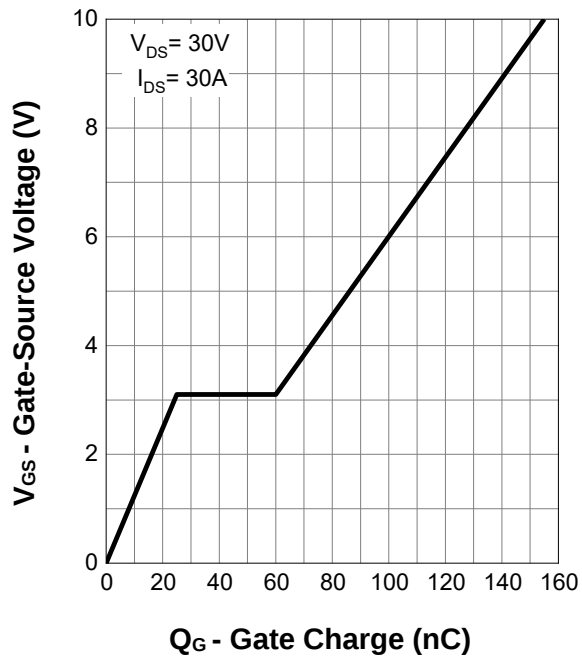
Diode Forward Current



Capacitance

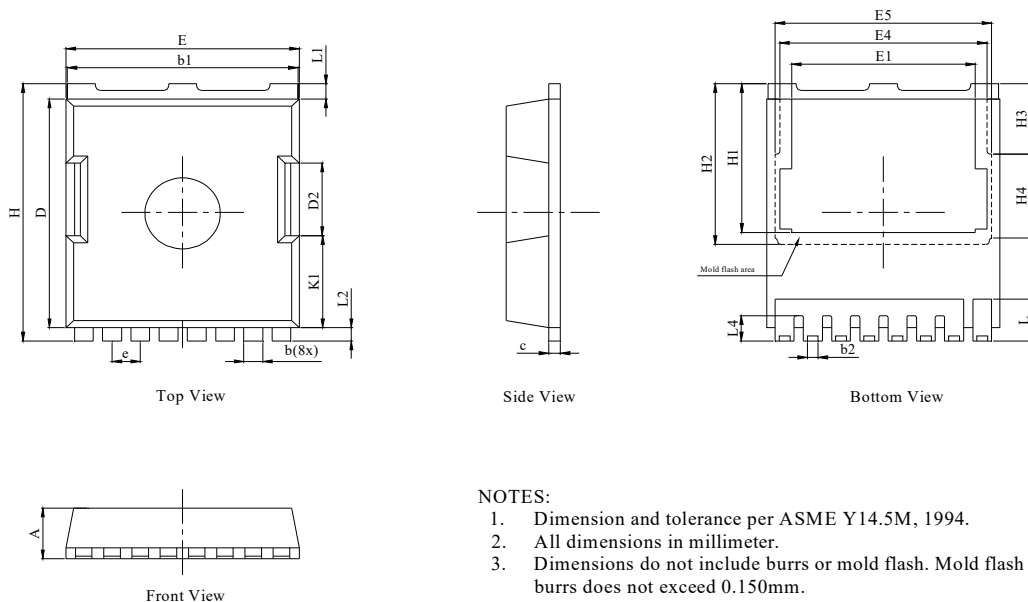


Gate Charge



Package Mechanical Data(TOLL-8L)

Package Outlines



NOTES:

1. Dimension and tolerance per ASME Y14.5M, 1994.
2. All dimensions in millimeter.
3. Dimensions do not include burrs or mold flash. Mold flash or burrs does not exceed 0.150mm.

DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b2	0.42	0.46	0.50
c	0.40	0.50	0.60
D	10.28	10.38	10.58
D2		3.30	
E	9.70	9.90	10.10
E1		7.80	
E4		8.80	
E5		9.20	
e	1.20 (BSC)		
H	11.48	11.68	11.88
H1	6.55	6.75	6.85
H2		7.30	
H3		3.20	
H4		3.80	
K1		4.18	
L	1.70	1.90	2.10
L1		0.70	
L2		0.60	
L4	1.00	1.15	1.30

Recommended Soldering Footprint

